

Amendments to the Abstract:

Please amend the Abstract as shown below:

Abstract of the Disclosure

An electrostatic chuck is provided, having an insulation layer ~~includes~~ including a mount plane on which a wafer is mounted, an inner electrode ~~provide~~ provided in the insulation layer, and projecting portions ~~protruded~~ protruding from the mount plane which include contact planes ~~to be contacted to~~ that contact the wafer. A backside gas ~~is flowed~~ flows into a space defined by the mount plane, the projecting portions, and the wafer under such a condition that the wafer is attracted to the mount plane so as to maintain a the temperature uniformity of the wafer. ~~A~~ The total ~~amount~~ of areas of the contact planes of the projecting portions is not less than 5% and not more than 10% with respect to ~~an~~ the area of the inner electrode, and the heights of the projecting portions are not less than 5 μm and not more than 10 μm .